METHOD OF MANUFACTURING FLASH MEMORY DEVICE

ABSTRACT OF THE DISCLOSURE



The present invention relates a method of manufacturing a flash memory device. In case of forming a dielectric film consisting of a lower oxide film, a nitride film and upper oxide film that is formed between a floating gate and a control gate, a nitrification process is performed after the lower oxide film is formed, thus forming a nitrogen layer below the lower oxide film. Then, an annealing process using an oxygen gas is performed to move the nitrogen layer onto the surface of the lower oxide film, thus forming a nitride film. Therefore, the present invention can reduce the effective thickness of the dielectric film.